
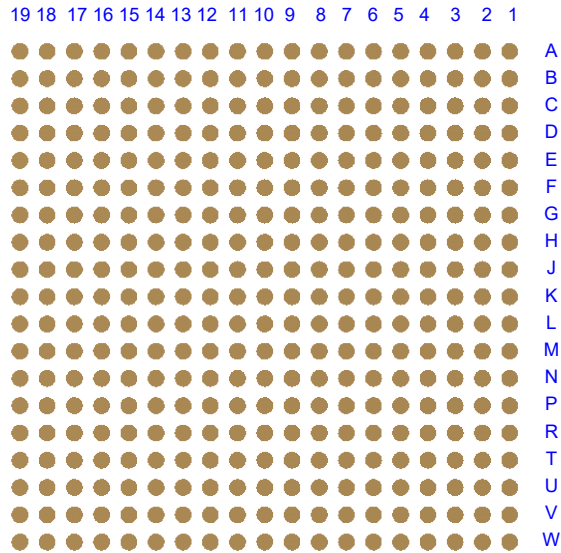


- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.45mm.
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.36mm [14 MIL].
 - 5) PAD Cu DIAMETER: 0.508mm [20 MIL].
 - 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

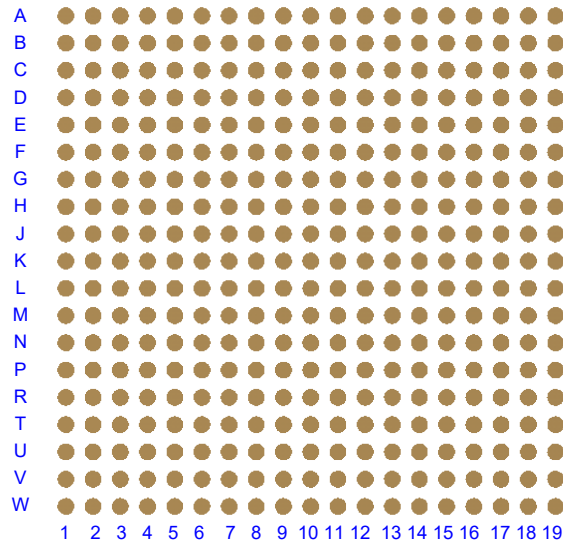
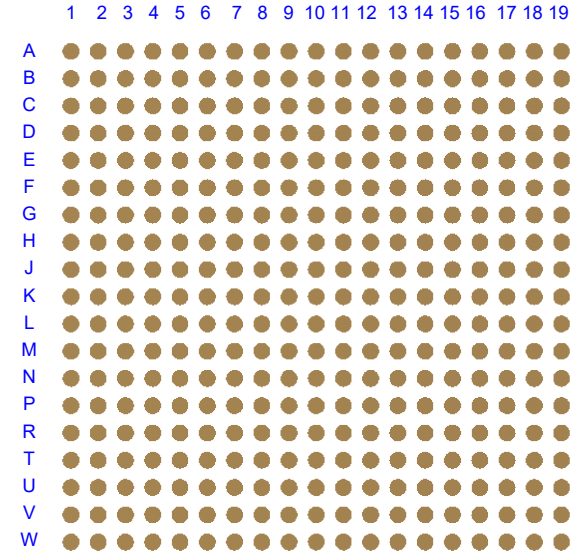
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA361T.8C-ISO	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	NO
BGA361T.8-ISO	Sn63/Pb37	Sn63	NO	NO

APPROVALS		DATE				
DRAWN	T. Au	2/18/2022				
ENG	M. Hart	2/18/2022	TITLE		BGA361T.8C-ISO ISOLATED DUMMY	
MFG			SCALE		DRAWING NO.	
QA			5.5:1	SIZE	581997	REV
CUST				A		A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 3

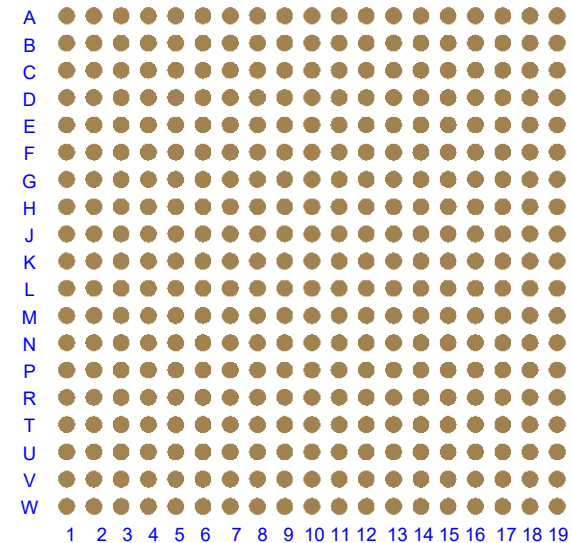
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

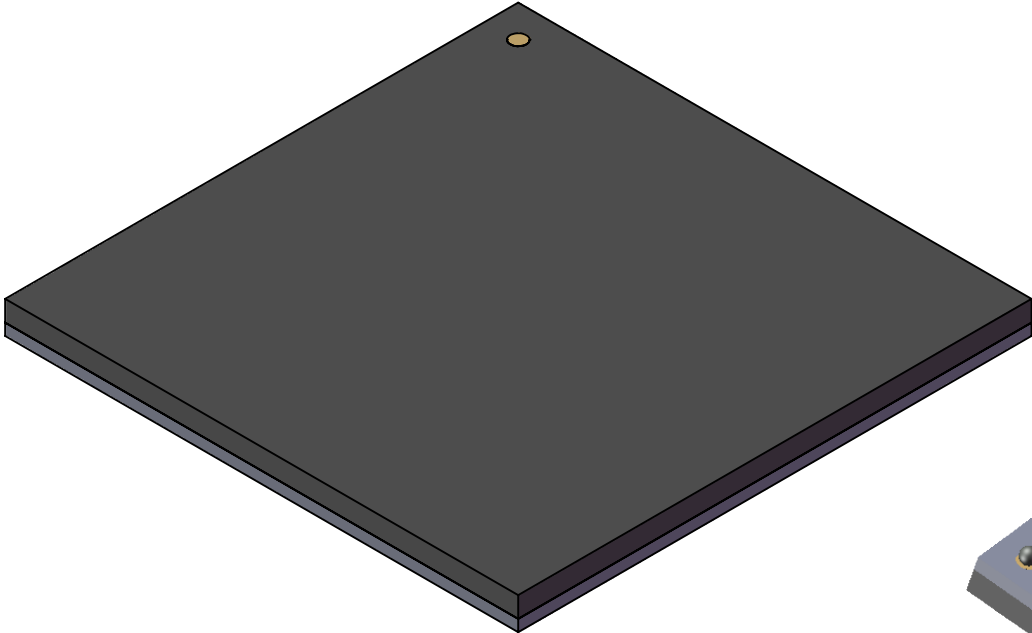
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm [20 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.36mm [14 MIL].

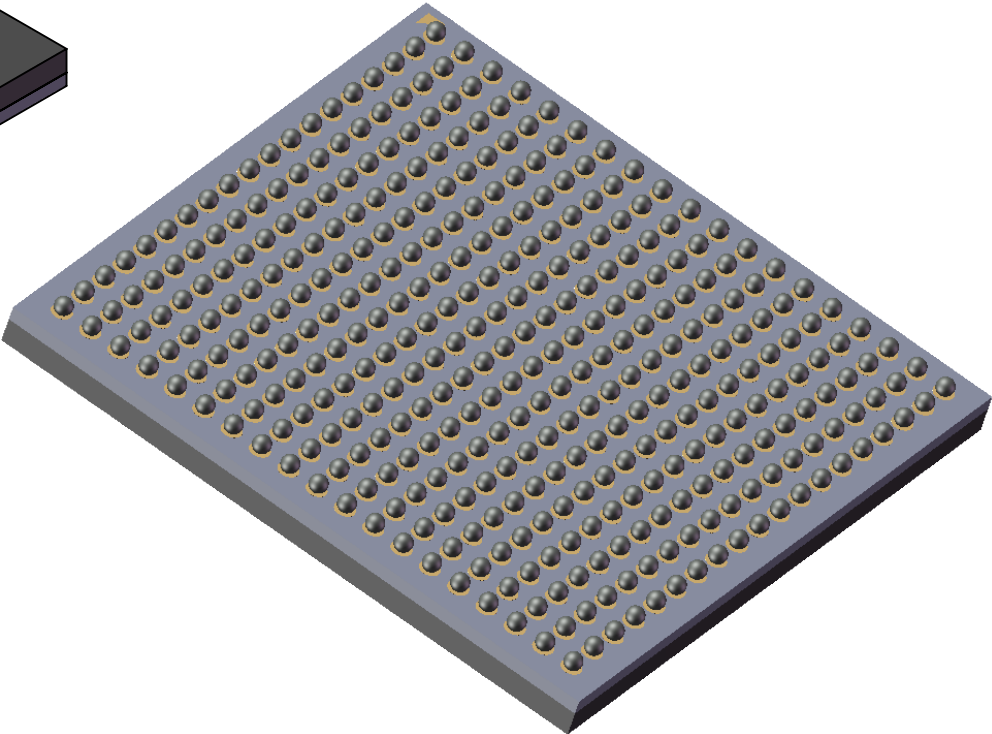
TopLine [®]			
TITLE		BGA361T.8C-ISO ISOLATED DUMMY	
SCALE	SIZE	DRAWING NO.	REV
4.5:1	A	581997	A
DO NOT SCALE DRAWING		SHEET 2 OF 3	

MODEL

TOP



BOTTOM



TopLine[®]

TITLE			
BGA361T.8C-ISO ISOLATED DUMMY			
SCALE	SIZE	DRAWING NO.	REV
2:1	A	581997	A
DO NOT SCALE DRAWING			SHEET 3 OF 3